


<b>PCN Number:</b>	20231031005.1		<b>PCN Date:</b>	October 31, 2023	
<b>Title:</b>	Qualification of RFAB using qualified Process Technology, Die Revision and Datasheet update for select devices				
<b>Customer Contact:</b>	Change Management team		<b>Dept:</b>	Quality Services	
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Jan 31, 2024		<b>Estimated Sample Availability:</b>	Dec 1, 2023*	
<b>*Sample requests received after December 1, 2023 will not be supported.</b>					
<b>Change Type:</b>					
<input type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process	
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments is pleased to announce the addition of RFAB using the LBC7 qualified process technology for the devices listed below.					
<b>Current Fab Site</b>			<b>Additional Fab Site</b>		
<b>Current Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>	<b>Additional Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>
DL-LIN	LBC2	150 mm	RFAB	LBC7	300 mm
The die was also changed as a result of the process change.					
The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.					
			<b>SN65LBC182, SN75LBC182</b> SLLS500B – MAY 2001 – REVISED OCTOBER 2023		
<b>Changes from Revision A (March 2005) to Revision B (October 2023)</b>					<b>Page</b>
• Changed the numbering format for tables, figures, and cross-references throughout the document.....					1
<b>Product Folder</b>	<b>Current Datasheet Number</b>	<b>New Datasheet Number</b>	<b>Link to full datasheet</b>		
SNx5LBC182	SLLS500A	<b>SLLS500B</b>	<a href="http://www.ti.com/product/SN65LBC182">http://www.ti.com/product/SN65LBC182</a>		
Qual details are provided in the Qual Data Section.					
<b>Reason for Change:</b>					
These changes are part of our multiyear plan to transition products from our 150- millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					

## Changes to product identification resulting from this PCN:

### Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>


### Die Rev:


Current


New

Die Rev [2P]	Die Rev [2P]
A	<b>A</b>

Sample product shipping label (not actual product label)


**TEXAS INSTRUMENTS**  
 MADE IN: Malaysia  
 2DC: 2Q:


**G4**



(1P) **SN74LS07NSR**  
 (Q) **2000** (D) **0336**  
 (31T) LOT: 3959047MLA  
 (4W) TKY (1T) 7523483SI2  
 (P)  
 (2P) REV: (V) **0033317**  
 (20L) CSO: SHE (21L) CCO:USA  
 (22L) ASO: MLA (23L) ACO: MYS

MSL '2 /260C/1 YEAR SEAL DT  
 MSL '1 /235C/UNLIM 03/29/04  
 OPT:  
 ITEM: 39  
**LBL: 5A (L)T0:1750**

### Product Affected:

SN65LBC182DR	SN65LBC182DRG4	SN65LBC182P	SN75LBC182DR
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For alternate parts with similar or improved performance, please visit the product page on [TI.com](https://www.ti.com)

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN65LBC182DR	Qual Device: SN75LBC182DR	Qual Device: SN65LBC182P	QBS Reference (Package): TCAN1044VDRQ1 (PG2.0)	QBS Reference (Package): TCAN1044VDRQ1 (PGL1/PGL0)	QBS Reference (Process): TPSS1217DSCR	QBS Reference (Process, Product): SN65HVD3080EDGSR	QBS Reference (Package): SN75179BP	QBS Reference (Package): TPSS4231DR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	2/154/0	-	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	1/77/0	2/154/0	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	1/77/0	2/154/0	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0	2/90/0	-	-	-	-
HTOL	B1	Life Test	135C	635 Hours	-	-	-	-	-	3/231/0	-	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	-	-	-	-	1/76/0	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	-	-	-	-	1/76/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder	-	-	-	-	-	-	-	-	-	3/66/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	-	-	-	-	-	3/15/0

Type	#	Test Name	Condition	Duration	Qual Device: SN65LBC182DR	Qual Device: SN75LBC182DR	Qual Device: SN65LBC182P	QBS Reference (Package): TCAN1044VDRQ1 (PG2.0)	QBS Reference (Package): TCAN1044VDRQ1 (PG1.1/PG1.0)	QBS Reference (Process): TPSS1217DSCR	QBS Reference (Process, Product): SN65HVD3089EDGSR	QBS Reference (Package): SN75179BP	QBS Reference (Package): TPSS4231DR
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	1/10/0	2/20/0	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	1/3/0	-	-	-	-	-	-
ESD	E2	ESD HBM (Bus Pins)	-	15000 Volts	1/3/0	-	-	-	-	-	-	-	-
ESD	E2	ESD HBM	-	3000 Volts	1/3/0	-	-	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	-	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	1/30/0	-	-	-	-	-	-

- QBS: Qual By Similarity
- Qual Device SN65LBC182DR is qualified at MSL1 260C
- Qual Device SN75LBC182DR is qualified at MSL1 260C
- Qual Device SN65LBC182P is qualified at NOT CLASSIFIED NOT CLASSIFIED
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2212-013

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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